

ABSTRACT OF THE DISCLOSURE

An integrated circuit package comprises an interposer having an opening, first and second surfaces and an outline. The interposer has first terminals and second terminals. The first terminals are electrically connected to the second terminals. A semiconductor chip adhered to the second surface of the interposer has an outline that is substantially the same as the outline of the interposer. The chip has at least one contact wire bonded to at least one of the first terminals. Encapsulant fills the opening to cover the wire bonding and the at least one contact.